

Appl. No. 10/709,664  
Amdt. dated January 20, 2006  
Reply to Office action of November 15, 2005

### REMARKS/ARGUMENTS

#### I. Rejection of claims 1-7, 9-13, and 15 under 35 U.S.C. 103(a):

Claims 1-7, 9-13, and 15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lebby taken with Yang in view of Yamazaki et al., all of record.

#### **Response:**

The applicant would like to point out the patentable differences between claim 1 and the cited prior art.

The present invention according to claim 1 recites that the first reaction layer and the second reaction layer are held together using a transparent adhesive layer, and the first and second reaction layers comprise metal material.

Yamazaki teaches in paragraph [0069], "As a method for forming the metal thin layer, there is a conventional known thin layer formation method, and typical examples of the suitable formation method include a sputtering process and a vacuum deposition method. Above all, **the sputtering process is preferable, because this process can suitably be utilized for the formation of the transparent conductive layer** which is to be laminated on the previously formed metal thin layer, and so these two layers can be formed and laminated by one apparatus using the sputtering process, which can lead to the improvement of a production efficiency."

From reading this, we know that the metal thin layer 15 (Ti,Cr) is inserted between the substrate 10 and the transparent conductive layer 20 (ITO) using a sputtering process. The transparent conductive layer 20 (ITO) is also adhered with the metal thin layer 15 (Ti,Cr) by the sputtering process.

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Yang teaches an adhesion promoter formed on the surface of the LED epitaxial structure by sputtering. Yang also teaches a BCB layer coated on a transparent substrate. Then Yang teaches bonding together the epitaxial layer with the promoter and the transparent substrate by BCB.

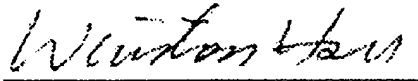
According to the above description, we can conclude that Yamazaki never teaches holding the transparent conductive layer 20 and the substrate 10 together with the metal thin layer 15, or bonding together the transparent conductive layer 20 and the metal thin layer 15 of the substrate 10. The transparent conductive layer 20 is just formed on the metal thin layer 15 by sputtering, not by bonding. Therefore, Yamazaki's metal thin layer used to enhance the adhesive properties of sputtering is not analogous to Yang's adhesion promoter provided by BCB bonding, and it would not be obvious to one skilled in the art to combine these two teachings.

Therefore, it is not obvious to use the metal (Ti,Cr) reaction layers to enhance the adhesion provided by the transparent adhesive layer, as is recited in claims 1 and 15. For these reasons, the currently amended claim 1 is patentably distinct from the cited prior art. Claims 2-7, 9-13, and 15 are dependent on claim 1, and should be allowed if claim 1 is allowed. Reconsideration of claims 1-7, 9-13, and 15 is therefore respectfully requested.

In light of the above arguments in favor of patentability, the applicant respectfully requests that a timely Notice of Allowance be issued in this case.

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Sincerely yours,



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